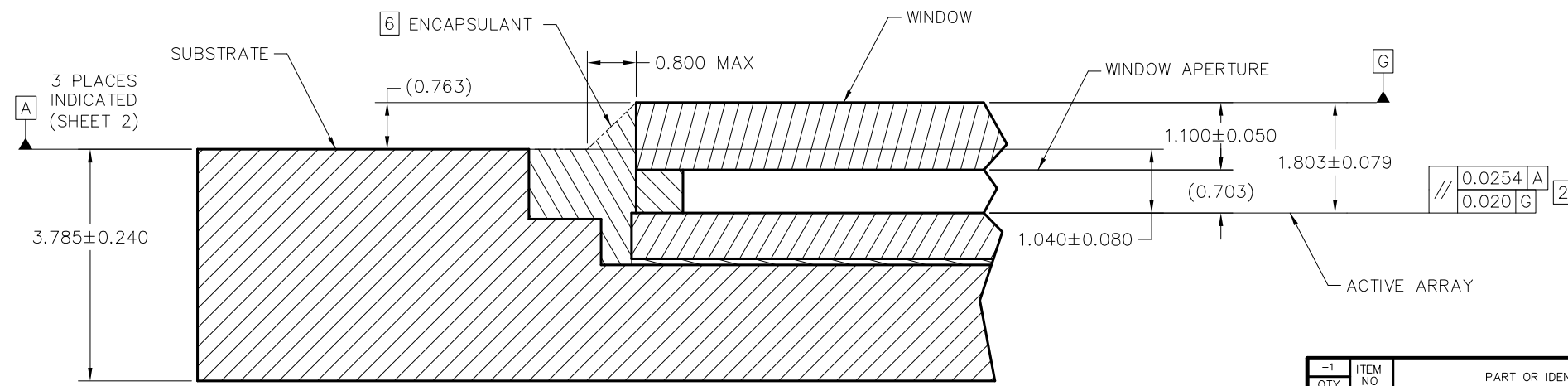
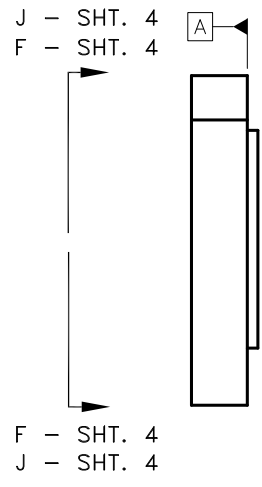
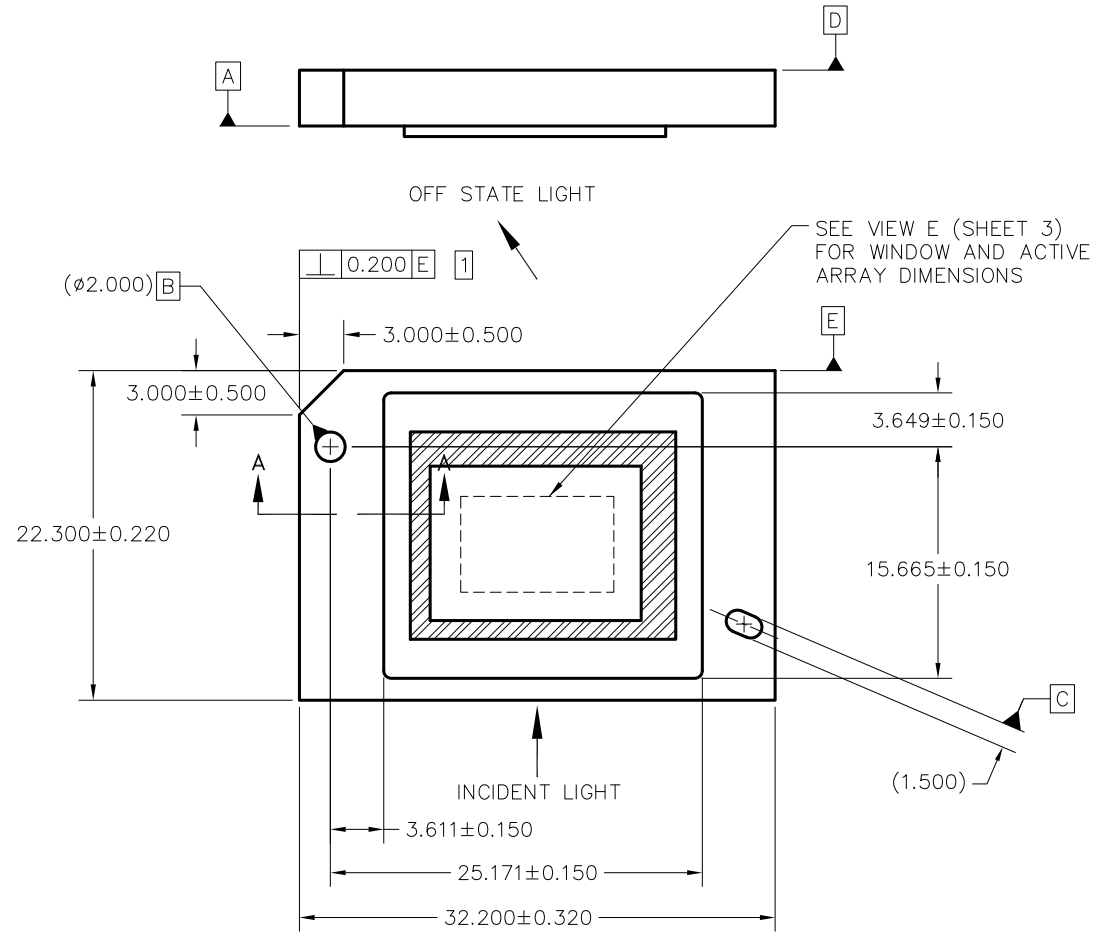


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	ECO 2159770, INITIAL RELEASE	07/28/2016	F. ARMSTRONG
B	ECO 2163097, ADD PRD TO SAP DESC; NO DWG CHG	12/16/2016	F. ARMSTRONG

NOTES: UNLESS OTHERWISE SPECIFIED:

- 1 SUBSTRATE EDGE PERPENDICULARITY TOLERANCE APPLIES TO ENTIRE SURFACE
- 2 DIE PARALLELISM TOLERANCE APPLIES TO DMD ACTIVE ARRAY ONLY
- 3 ROTATION ANGLE OF DMD ACTIVE ARRAY IS A REFINEMENT OF THE LOCATION TOLERANCE AND HAS A MAXIMUM ALLOWED VALUE OF 0.8 DEGREES
- 4 SUBSTRATE SYMBOLIZATION PAD, AND PLATING AT BOTTOM OF DATUMS B AND C HOLES TO BE ELECTRICALLY CONNECTED TO VSS PLANE WITHIN THE SUBSTRATE
- 5 BOUNDARY MIRRORS SURROUNDING THE DMD ACTIVE AREA
- 6 MAXIMUM ENCAPSULANT PROFILE SHOWN
- 7 ENCAPSULANT ALLOWED ON THE SURFACE OF THE CERAMIC IN THE AREA SHOWN IN VIEW B (SHEET 2). ENCAPSULANT SHALL NOT EXCEED 0.200 THICKNESS MAXIMUM.
- 8 SUBSTRATES PLATED WITH Ni/Au SHALL HAVE THE THREE-DIGIT NUMERICAL MARKING IN THE AREA TO THE LEFT OF THE SYMBOLIZATION PAD. SUBSTRATES PLATED WITH Ni/Pd/Au SHALL HAVE THE MARKING IN THE AREA TO THE RIGHT OF THE SYMBOLIZATION PAD.

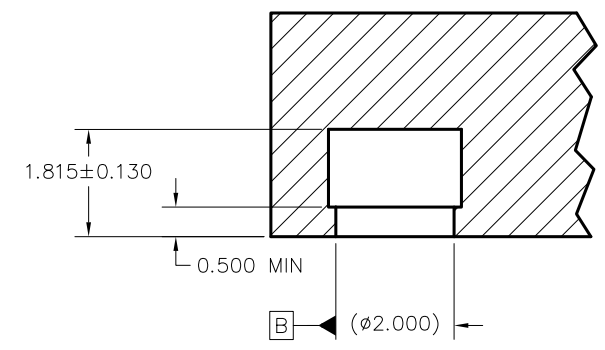


SECTION A-A
SCALE 20/1

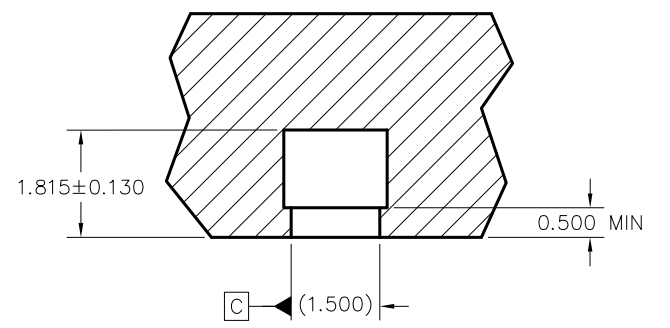
QTY	ITEM NO	PART OR IDENTIFYING NUMBER	NOMENCLATURE OR DESCRIPTION	NOTES
-1				

PARTS LIST		UNLESS OTHERWISE SPECIFIED	
DWN	F. ARMSTRONG	DATE	07/13/16
ENGR	F. ARMSTRONG	DATE	07/13/16
QA	P. KONRAD	DATE	08/03/16
COE	M. DORAK	DATE	08/03/16

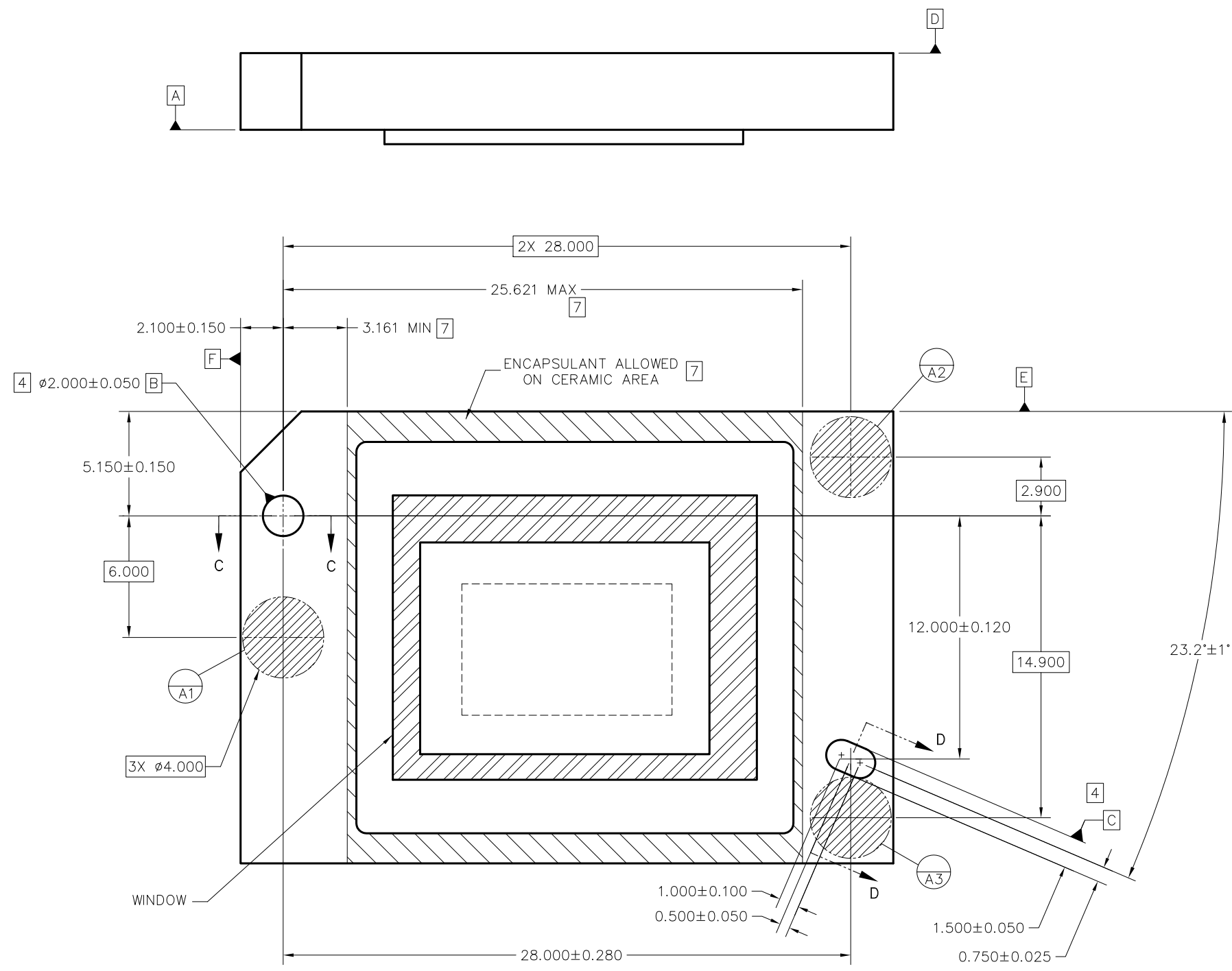
TEXAS INSTRUMENTS Dallas, Texas	ICD, MECHANICAL, DMD .48" WUXGA MTRP 2xLVDS HB SERIES 410 (FXG PACKAGE)
SIZE B	DRAWING NO 2515167
SCALE 4/1	REV B
	SHEET 1 OF 4



SECTION C-C
DATUM B
SCALE 16/1



SECTION D-D
DATUM C
SCALE 16/1



VIEW B
DATUMS AND ENCAPSULANT ALLOWABLE AREA
SCALE 8/1

8

7

6

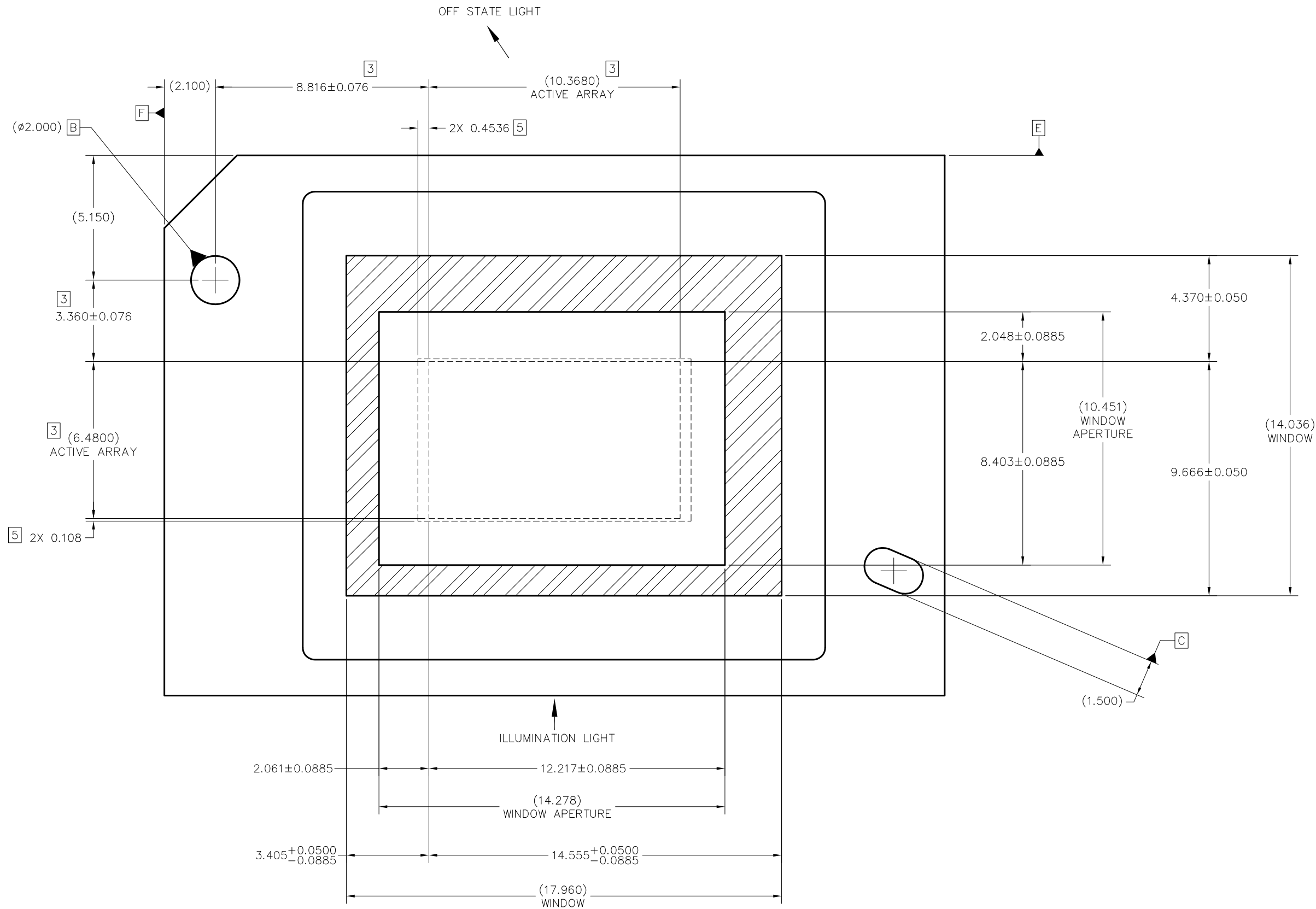
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4

3

DWG NO 2515167 SH 3

1



VIEW E (SHEET 1)
 DMD WINDOW AND ACTIVE ARRAY
 SCALE 12:1

 TEXAS INSTRUMENTS Dallas, Texas	DWN	DATE	SIZE	DRAWING NO	REV
	ISSUE DATE	SCALE	4/1	2515167	B
				SHEET	3

8

7

6

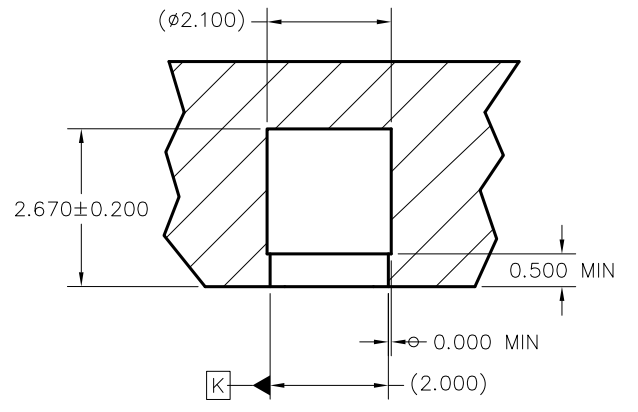
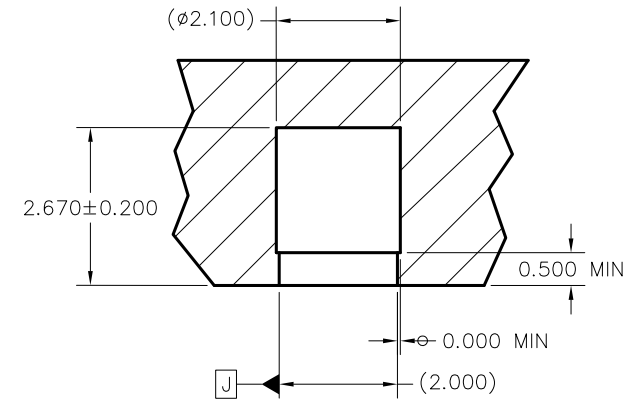
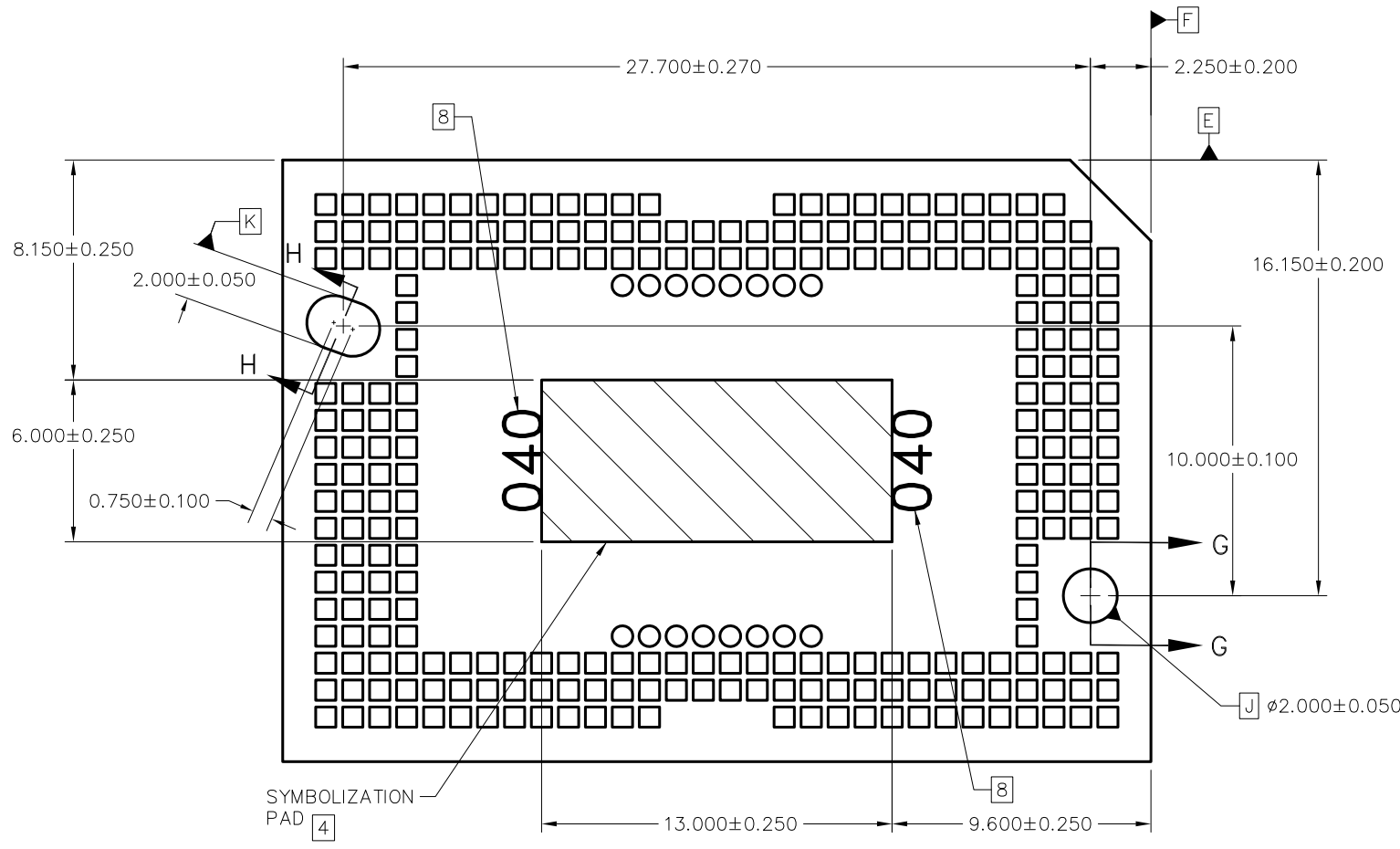
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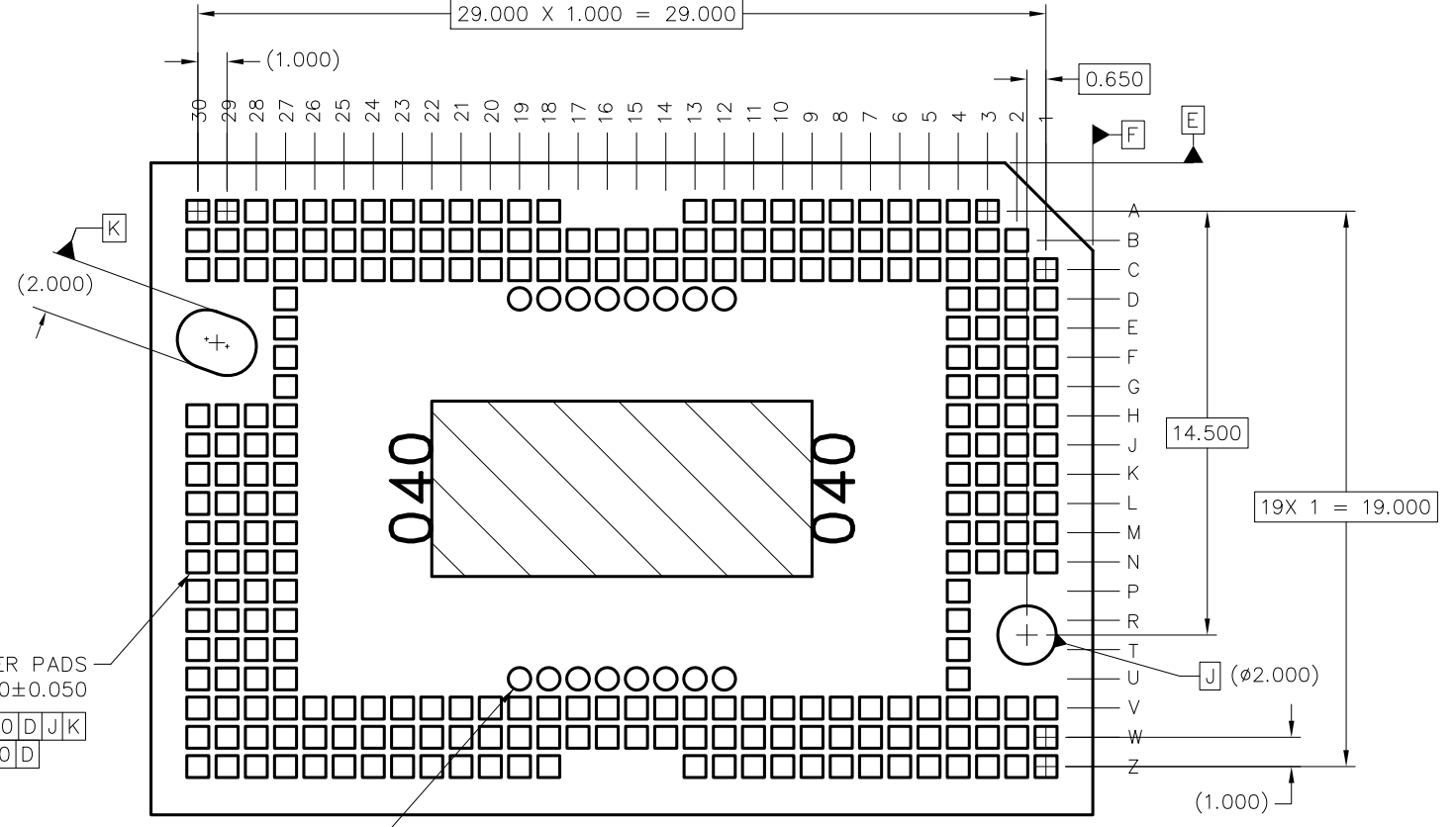
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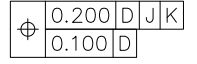
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VIEW F-F (SHEET 1)
DATUMS J AND K, SYMBOLIZATION PAD
SCALE 8/1



257X LGA CUSTOMER PADS
0.750±0.050 X 0.750±0.050



16X LGA TEST PADS
DO NOT CONNECT

VIEW J-J (SHEET 1)
LGA PADS
SCALE 8/1

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